

Frequency Generator & Integrated Buffers for PENTIUM/Pro™ & K6

General Description

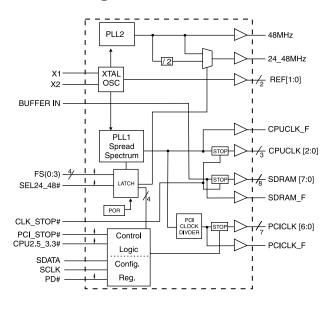
The ICS9248-101 is the single chip clock solution for Notebook designs using the 440BX or the VIA Apollo Pro 133 style chipset. It provides all necessary clock signals for such a system.

Spread spectrum may be enabled through I²C programming. Spread spectrum typically reduces system EMI by 8dB to 10dB. This simplifies EMI qualification without resorting to board design iterations or costly shielding. The ICS9248-101 employs a proprietary closed loop design, which tightly controls the percentage of spreading over process and temperature variations.

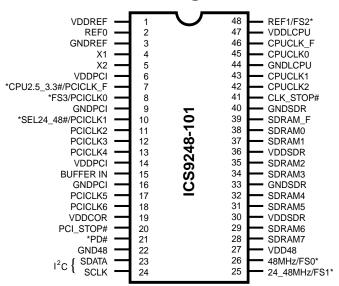
Features

- Up to 137MHz frequency support
- Spread Spectrum for EMI control
- Serial I²C interface for Power Management, Frequency Select, Spread Spectrum.
- Provides the following system clocks
 - 4-CPUs @ 2.5/3.3V, up to 137MHz. (including CPUCLK F)
 - 9-SDRAMs @3.3V, up to 137MHz (including SDRAM_F)
 - 8-PCI @3.3V, CPU/2 or CPU/3 (including 1 free running PCICLK_F)
 - 1-24/48MHz@3.3V
 - -1-48MHz@3.3V fixed
 - 2-REF @3.3V, 14.318MHz.
- Efficient Power management scheme through PCI and STOP CLOCKS
- Spread Spectrum \pm .25%, & 0 to -0.5% down spread

Block Diagram



Pin Configuration



Power Groups

VDDLCPU, GNDLCPU=CPUCLK [2:0], CPUCLK_F VDDSDR, GNDSDR=SDRAMCLKS [7:0], SDRAM_F VDDPCI, GNDPCI=PCICLKS [6:0], PCICLK_F VDD48, GND48=48MHz, 24MHz VDDREF, GNDREF=REF, X1, X2 VDDCOR=PLLCORE

48-Pin SSOP and TSSOP

* Internal Pull-up Resistor of 120K to VDD

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Pin Descriptions

PIN NUMBER	PIN NAME	ТҮРЕ	DESCRIPTION			
1	VDDREF	PWR	Ref, XTAL power supply, nominal 3.3V			
2	REF0	OUT	14.318 Mhz reference clock.This REF output is the STRONGER buffer for ISA BUS loads			
20	PCI_STOP#	IN	Halts PCICLK [6:0]clocks at logic 0 level, when input low (In mobile mode, MODE=0)			
3, 9, 16, 33, 40, 44	GND	PWR	Ground			
4	X1	IN	Crystal input, has internal load cap (36pF) and feedback resistor from X2			
5	X2	OUT	Crystal output, nominally 14.318MHz.			
6,14	VDDPCI	PWR	Supply for PCICLK_F and PCICLK [6:0], nominal 3.3V			
7	CPU2.5_3.3#1,2	IN	Indicates whether VDDLCPU is 2.5 or 3.3V. High=2.5V CPU, LOW=3.3V CPU. Latched Input.			
,	PCICLK_F	OUT	Free running PCI clock not affected by PCI_STOP# for power management.			
0	FS3 ^{1,2}	IN	Frequency select pin. Latched Input.			
8	PCICLK0	OUT	PCI clock output. Synchronous to CPU clocks with 1-4ns skew (CPU early)			
10	SEL24_48#1,2	IN	Selects either 24 or 48MHz when Low =48 MHz			
10	PCICLK1	OUT	PCI clock output. Synchronous to CPU clocks with 1-4ns skew (CPU early)			
18, 17, 13, 12, 11,	PCICLK [6:2]	OUT	PCI clock outputs. Synchronous to CPU clocks with 1-4ns skew (CPU early)			
15	BUFFER IN	IN	nput to Fanout Buffers for SDRAM outputs.			
19	VDDCOR	PWR	Power pin for the PLL core. 3.3V			
21	PD#1	IN	Asynchronous active low input pin used to power down the device into a low power state. The internal clocks are disabled and the VCO and the crystal are stopped. The latency of the powdown will not be greater than 4ms.			
22	GND48	PWR	Ground pin for the 24 & 48MHz output buffers & fixed PLL core.			
28, 29, 31, 32, 34, 35, 37, 38	SDRAM [7:0]	OUT	SDRAM clock outputs, Fanout Buffer outputs from BUFFER IN pin (controlled by chipset).			
30, 36	VDDSDR	PWR	Supply for SDRAM [7:0] and CPU PLL Core, nominal 3.3V.			
23	SDATA	IN	Data input for I ² C serial input, 5V tolerant input			
24	SCLK	IN	Clock input of I ² C input, 5V tolerant input			
25	24_48MHz	OUT	24MHz or 48MHz output clock selectable by pin 10			
25	FS1 ^{1, 2}	IN	Frequency select pin. Latched Input.			
26	48MHz	OUT	48MHz output clock			
26	FS01, 2	IN	Frequency select pin. Latched Input			
27	VDD48	PWR	Power for 24 & 48MHz output buffers and fixed PLL core.			
39	SDRAM_F	OUT	Free running SDRAM clock output. Not affected by CPU_STOP#			
41	CLK_STOP#	IN	This asynchronous input halts CPUCLK(0:2), & SDRAM (0:7) at logic "0" level when driven low.			
42, 43, 45	CPUCLK [2:0]	OUT	CPU clock outputs, powered by VDDLCPU			
46	CPUCLK_F	OUT	Free running CPU clock. Not affected by the CPU_STOP#			
47	VDDLCPU	PWR	Supply for CPU clocks 2.5V			
40	REF1	OUT	14.318 MHz reference clock.			
48	FS2 ^{1, 2}	IN	Frequency select pin. Latched Input			

- 1: Internal Pull-up Resistor of 120K to 3.3V on indicated inputs
- 2: Bidirectional input/output pins, input logic levels are latched at internal power-on-reset. Use 10Kohm resistor to program logic Hi to VDD or GND for logic low.



General I²C serial interface information

The information in this section assumes familiarity with I²C programming. For more information, contact ICS for an I²C programming application note.

How to Write:

- Controller (host) sends a start bit.
- Controller (host) sends the write address D2 (H)
- ICS clock will acknowledge
- Controller (host) sends a dummy command code
- ICS clock will acknowledge
- Controller (host) sends a dummy byte count
- ICS clock will acknowledge
- Controller (host) starts sending first byte (Byte 0) through byte 5
- ICS clock will acknowledge each byte one at a time.
- Controller (host) sends a Stop bit

How to Write:						
Controller (Host)	ICS (Slave/Receiver)					
Start Bit						
Address						
D2 _(H)						
	ACK					
Dummy Command Code						
	ACK					
Dummy Byte Count						
	ACK					
Byte 0						
	ACK					
Byte 1						
	ACK					
Byte 2						
	ACK					
Byte 3						
	ACK					
Byte 4						
	ACK					
Byte 5						
-	ACK					
Stop Bit						

How to Read:

- Controller (host) will send start bit.
- Controller (host) sends the read address D3 (H)
- ICS clock will acknowledge
- ICS clock will send the *byte count*
- Controller (host) acknowledges
- ICS clock sends first byte (Byte 0) through byte 5
- Controller (host) will need to acknowledge each byte
- Controller (host) will send a stop bit

How to Read:					
Controller (Host)	ICS (Slave/Receiver)				
Start Bit					
Address					
D3 _(H)					
	ACK				
	Byte Count				
ACK					
	Byte 0				
ACK					
	Byte 1				
ACK					
	Byte 2				
ACK					
	Byte 3				
ACK					
	Byte 4				
ACK					
	Byte 5				
ACK					
Stop Bit					

- 1. The ICS clock generator is a slave/receiver, I²C component. It can read back the data stored in the latches for verification. **Read-Back will support Intel PIIX4 "Block-Read" protocol**.
- 2. The data transfer rate supported by this clock generator is 100K bits/sec or less (standard mode)
- 3. The input is operating at 3.3V logic levels.
- 4. The data byte format is 8 bit bytes.
- 5. To simplify the clock generator I²C interface, the protocol is set to use only "**Block-Writes**" from the controller. The bytes must be accessed in sequential order from lowest to highest byte with the ability to stop after any complete byte has been transferred. The Command code and Byte count shown above must be sent, but the data is ignored for those two bytes. The data is loaded until a Stop sequence is issued.
- 6. At power-on, all registers are set to a default condition, as shown.



Functionality

 V_{DD} = 3.3V±5%, V_{DDL} = 2.5V±5% or 3.3±5%, TA=0 to 70°C Crystal (X1, X2) = 14.31818MHz

FS3	FS2	FS1	FS0	CPU	PCI
1.55	102	151	150	(MHz)	(MHz)
0	0	0	0	124.00	41.33
0	0	0	1	120.00	40.00
0	0	1	0	114.99	38.33
0	0	1	1	109.99	36.66
0	1	0	0	105.00	35.00
0	1	0	1	83.31	41.65
0	1	1	0	137.00	34.25
0	1	1	1	75.00	37.50
1	0	0	0	100.00	33.33
1	0	0	1	95.00	31.67
1	0	1	0	83.31	27.77
1	0	1	1	133.33	33.33
1	1	0	0	90.00	30.00
1	1	0	1	96.22	32.07
1	1	1	0	66.82	33.41
1	1	1	1	91.5	30.5

Serial Configuration Command BitmapByte0: Functionality and Frequency Select Register (default = 0)

Bit		Description		PWD
Bit 7	0 - ±0.25% Spread Sp 1 - 0 to -0.5% Down S	n, Center Spread	1	
	Bit [2, 6:4]	CPUCLK (MHz)	PCICLK (MHz)	
	0000	124.00	41.33	
	0001	120.00	40.00	
	0010	114.99	38.33	
	0011	109.99	36.66	
	0100	105.00	35.00	
	0101	83.31	41.65	
	0110	137.00	34.25	Note1
Bit [2, 6:4]	0111	75.00	37.50	Note1
[2, 0.4]	1000	100.00	33.33	
	1001	95.00	31.67	
	1010	83.31	27.77	
	1011	133.33	33.33	
	1100	90.00	30.00	
	1101	96.22	32.07	
	1110	66.82	33.41	
	1111	91.5	30.5	
Bit 3		0		
Bit 1		Enabled		1
Bit 0	0 - Running 1- Tristate all outputs	Bit [2, 6:4] CPUCLK (MHz) PCICLK (MHz) 0000 124.00 41.33 0001 120.00 40.00 0010 114.99 38.33 0011 109.99 36.66 0100 105.00 35.00 0101 83.31 41.65 0110 137.00 34.25 0111 75.00 37.50 1000 100.00 33.33 1001 95.00 31.67 1010 83.31 27.77 1011 133.33 33.33 1100 90.00 30.00 1101 96.22 32.07 1110 66.82 33.41 1111 91.5 30.5 Frequency is selected by hardware select, latched inputs Frequency is selected by Bit [2, 6:4] Normal Spread Spectrum Enabled Running		

- 1, Default at Power-up will be for latched logic inputs to define frequency. Bit [2, 6:4] are default to 0010.
- 2, PWD = Power-Up Default
- 3, When disabling spread spectrum bit7 needs to be set to 0 to maintain nominal frequency.



Byte 1: CPU, Active/Inactive Register (1 = enable, 0 = disable)

Bit	Pin #	PWD	Description
Bit 7	-	1	(Reserved)
Bit 6	46	1	CPUCLK_F (Act/Inact)
Bit 5	-	1	(Reserved)
Bit 4	-	1	(Reserved)
Bit 3	39	1	SDRAM_F (Act/Inact)
Bit 2	42	1	CPUCLK2 (Act/Inact)
Bit 1	43	1	CPUCLK1 (Act/Inact)
Bit 0	45	1	CPUCLK0 (Act/Inact)

Byte 2: PCI Active/Inactive Register (1 = enable, 0 = disable)

Bit	Pin #	PWD	Description
Bit 7	7	1	PCICLK_F (Act/Inact)
Bit 6	18	1	PCICLK6 (Act/Inact)
Bit 5	17	1	PCICLK5 (Act/Inact)
Bit 4	13	1	PCICLK4 (Act/Inact)
Bit 3	12	1	PCICLK3 (Act/Inact)
Bit 2	11	1	PCICLK2 (Act/Inact)
Bit 1	10	1	PCICLK1 (Act/Inact)
Bit 0	8	1	PCICLK0 (Act/Inact)

Byte 3: SDRAM Active/Inactive Register (1 = enable, 0 = disable)

Bit	Pin #	PWD	Description
Bit 7	-	1	(Reserved)
Bit 6	-	1	(Reserved)
Bit 5	-	1	(Reserved)
Bit 4	-	1	(Reserved)
Bit 3	28	1	SDRAM7 (Active/Inactive)
Bit 2	29	1	SDRAM6 (Active/Inactive)
Bit 1	31	1	SDRAM5 (Active/Inactive)
Bit 0	32	1	SDRAM4 (Active/Inactive)

- 1. Inactive means outputs are held LOW and are disabled from switching.
- 2. Latched Frequency Selects (FS#) will be inverted logic load of the input frequency select pin conditions.



Byte 4: Reserved Active/Inactive Register (1 = enable, 0 = disable)

Bit	Pin #	PWD	Description
DIL	FIII#	PWD	Description
Bit 7	-	1	(Reserved)
Bit 6	-	1	(Reserved)
Bit 5	-	1	(SEL24_48)#
Bit 4	-	1	(Reserved)
Bit 3	-	X	Latched FS1#
Bit 2	-	1	(Reserved)
Bit 1	-	X	Latched FS3#
Bit 0	-	1	(Reserved)

Byte 5: Peripheral Active/Inactive Register (1 = enable, 0 = disable)

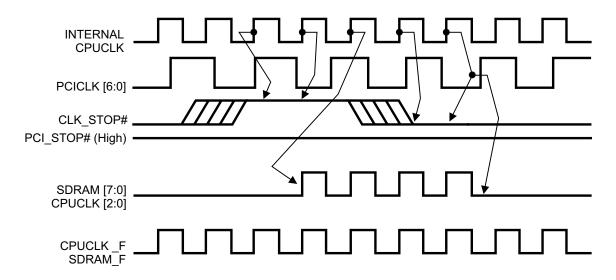
Bit	Pin #	PWD	Description
Bit 7	34	1	SDRAM3 (Act/Inact)
Bit 6	35	1	SDRAM2 (Act/Inact)
Bit 5	37	1	SDRAM1 (Act/Inact)
Bit 4	38	1	SDRAM0 (Act/Inact)
Bit 3	26	1	48MHz (Act/Inact)
Bit 2	25	1	24MHz (Act/Inact)
Bit 1	48	1	REF1 (Act/Inact)
Bit 0	2	1	REF0 (Act/Inact)

- 1. Inactive means outputs are held LOW and are disabled from switching.
- 2. Latched Frequency Selects (FS#) will be inverted logic load of the input frequency select pin conditions.



CLK_STOP# Timing Diagram

CLK_STOP# is an asychronous input to the clock synthesizer. It is used to turn off the CPU clocks for low power operation. CLK_STOP# is synchronized by the **ICS9248-101**. The minimum that the CPU clock is enabled (CLK_STOP# high pulse) is 100 CPU clocks. All other clocks will continue to run while the CPU clocks are disabled. The CPU clocks will always be stopped in a low state and start in such a manner that guarantees the high pulse width is a full pulse. CPU clock on latency is less than 4 CPU clocks and CPU clock off latency is less than 4 CPU clocks.



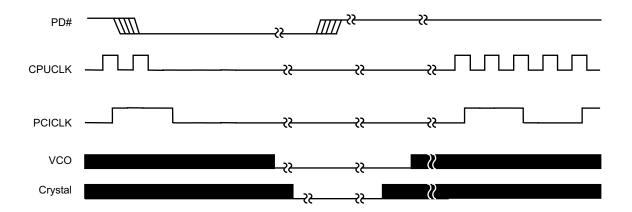
- 1. All timing is referenced to the internal CPU clock.
- CLK_STOP# is an asynchronous input and metastable conditions may exist. This signal is synchronized to the CPU clocks inside the ICS9248-101.
- 3. SDRAM-F output is controlled by Buffer in signal, not affected by the ICS9248-101 CLK_STOP# signal. SDRAM [7:0] are controlled as shown.
- 4. All other clocks continue to run undisturbed.



PD# Timing Diagram

The power down selection is used to put the part into a very low power state without turning off the power to the part. PD# is an asynchronous active low input. This signal needs to be synchronized internal to the device prior to powering down the clock synthesizer.

Internal clocks are not running after the device is put in power down. When PD# is active low all clocks need to be driven to a low value and held prior to turning off the VCOs and crystal. The power up latency needs to be less than 4 mS. The power down latency should be as short as possible but conforming to the sequence requirements shown below. PCI_STOP# and CLK_STOP# are considered to be don't cares during the power down operations. The REF and 48MHz clocks are expected to be stopped in the LOW state as soon as possible. Due to the state of the internal logic, stopping and holding the REF clock outputs in the LOW state may require more than one clock cycle to complete.

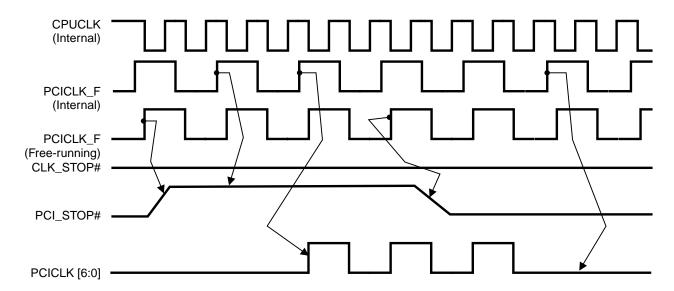


- 1. All timing is referenced to the Internal CPUCLK (defined as inside the ICS9248 device).
- 2. As shown, the outputs Stop Low on the next falling edge after PD# goes low.
- 3. PD# is an asynchronous input and metastable conditions may exist. This signal is synchronized inside this part.
- 4. The shaded sections on the VCO and the Crystal signals indicate an active clock.
- 5. Diagrams shown with respect to 133MHz. Similar operation when CPU is 100MHz.



PCI_STOP# Timing Diagram

PCI_STOP# is an asynchronous input to the **ICS9248-101**. It is used to turn off the PCICLK [6:0] clocks for low power operation. PCI_STOP# is synchronized by the **ICS9248-101** internally. The minimum that the PCICLK [6:0] clocks are enabled (PCI_STOP# high pulse) is at least 10 PCICLK [6:0] clocks. PCICLK [6:0] clocks are stopped in a low state and started with a full high pulse width guaranteed. PCICLK [6:0] clock on latency cycles are only three rising PCICLK clocks, off latency is one PCICLK clock.



- 1. All timing is referenced to the Internal CPUCLK (defined as inside the ICS9248 device.)
- 2. PCI_STOP# is an asynchronous input, and metastable conditions may exist. This signal is required to be synchronized inside the ICS9248.
- 3. All other clocks continue to run undisturbed.
- 4. CLK STOP# is shown in a high (true) state.



Shared Pin Operation - Input/Output Pins

The I/O pins designated by (input/output) on the ICS9248-101 serve as dual signal functions to the device. During initial power-up, they act as input pins. The logic level (voltage) that is present on these pins at this time is read and stored into a 4-bit internal data latch. At the end of Power-On reset, (see AC characteristics for timing values), the device changes the mode of operations for these pins to an output function. In this mode the pins produce the specified buffered clocks to external loads.

To program (load) the internal configuration register for these pins, a resistor is connected to either the VDD (logic 1) power supply or the GND (logic 0) voltage potential. A 10 Kilohm(10K) resistor is used to provide both the solid CMOS programming voltage needed during the power-up programming period and to provide an insignificant load on the output clock during the subsequent operating period.

Figs. 1 and 2 show the recommended means of implementing this function. In Fig. 1 either one of the resistors is loaded onto the board (selective stuffing) to configure the device's internal logic. Figs. 2a and b provide a single resistor loading option where either solder spot tabs or a physical jumper header may be used.

These figures illustrate the optimal PCB physical layout options. These configuration resistors are of such a large ohmic value that they do not effect the low impedance clock signals. The layouts have been optimized to provide as little impedance transition to the clock signal as possible, as it passes through the programming resistor pad(s).

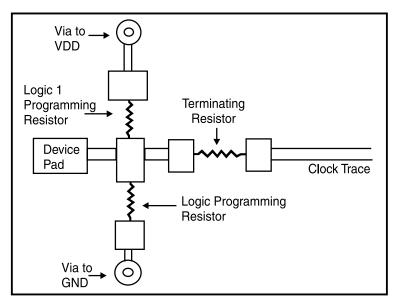


Fig. 1



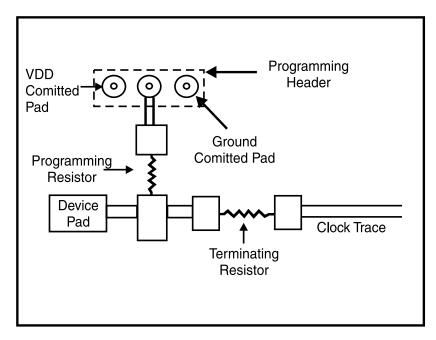


Fig. 2a

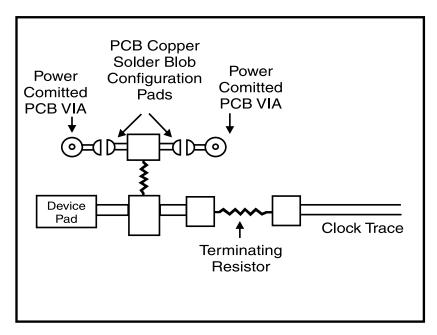


Fig. 2b



Absolute Maximum Ratings

Supply Voltage..... 7.0 V

Logic Inputs GND -0.5 V to $V_{DD} + 0.5$ V

Ambient Operating Temperature 0° C to $+70^{\circ}$ C

Case Temperature 115°C

Stresses above those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only and functional operation of the device at these or any other conditions above those listed in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Electrical Characteristics - Input/Supply/Common Output Parameters

 $T_A = 0 - 70C$; Supply Voltage $V_{DD} = V_{DDL} = 3.3 \text{ V} + /-5\%$ (unless otherwise stated)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Input High Voltage	V_{IH}		2		$V_{\rm DD} + 0.3$	V
Input Low Voltage	VIL		Vss-0.3		0.8	V
On a mation of Community		C _L = 0 pF; Select @ 66MHz		90	150	
Operating Supply Current	$I_{DD3.3OP}$	C _L = 0 pF; Select @ 100MHz		120	170	mA
Cullent		C _L = 0 pF; Select @ 133MHz		151	180	
Powerdown Current	I_{DDPD}	CL = 0 pF; Input address VDD or GND		250	600	μA
Input Frequency	Fi	$V_{DD} = 3.3 \text{ V}$	12	14.318	16	MHz
Input Capacitance ¹	Cin	Logic Inputs			5	pF
	Cinx	X1 & X2 pins	27	36	45	pF
Clk Stabilization ¹	Tstab	From $V_{DD} = 3.3 \text{ V to } 1\% \text{ target Freq.}$			5.5	ms
Skew ¹	tcpu-pcii	$V_T = 1.5 \text{ V}$	1	2.8	4	ns

¹Guaranteed by design, not 100% tested in production.

Electrical Characteristics - Input/Supply/Common Output Parameters

 $TA = 0 - 70^{\circ} C$; Supply Voltage VDD = 3.3 V + /-5%, VDDL = 2.5 V + /-5% (unless otherwise stated)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Operating SupplyCurrent		CL = 0 pF; Select @ 66.8 MHz		8	15	
		C _L = 0 pF; Select @ 100 MHz		11	18	mA
		C _L = 0 pF; Select @ 133 MHz		17	20	
Powerdown Current	Iddlpd	CL = 0 pF; Input address VDD or GND		<1	10	μΑ
Skew ¹	tcpu-pci2	$V_T = 1.5 \text{ V}; V_{TL} = 1.25 \text{ V}$	1	2.4	4	ns

¹Guaranteed by design, not 100% tested in production.



Electrical Characteristics - CPU

 T_A = 0 - 70C; V_{DD} = 3.3 V +/-5%; C_L = 20 pF

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output High Voltage	V_{OH2A}	$I_{OH} = -20 \text{ mA}$	2.4	2.85		V
Output Low Voltage	V_{OL2A}	$I_{OL} = 12 \text{ mA}$		0.31	0.4	V
Output High Current	I_{OH2A}	$V_{OH} = 2.0 \text{ V}$		-45	-27	mA
Output Low Current	I_{OL2A}	$V_{OL} = 0.8 \text{ V}$	22	29		mA
Rise Time ¹	t_{r2A}	$V_{OL} = 0.4 \text{ V}, V_{OH} = 2.4 \text{ V}$		1.5	2	ns
Fall Time ¹	$t_{\rm f2A}$	$V_{OH} = 2.4 \text{ V}, V_{OL} = 0.4 \text{ V}$		1.4	2	ns
Duty Cycle ¹	d_{t2A}	$V_T = 1.5 \text{ V}$	45		55	%
Skew window ¹	t _{sk2A}	$V_T = 1.5 \text{ V}$		80	175	ps
Jitter, Cycle-to-cycle ¹	t _{jcyc-cyc2A}	$V_T = 1.5 \text{ V}$		200	250	ps

¹Guaranteed by design, not 100% tested in production.

Electrical Characteristics - CPU

 $T_A = 0$ - 70C; $V_{DDL} = 2.5 \text{ V} + /-5\%$; $C_L = 20 \text{ pF}$

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output High Voltage	V_{OH2B}	$I_{OH} = -12 \text{ mA}$	2	2.3		V
Output Low Voltage	V_{OL2B}	$I_{OL} = 12 \text{ mA}$		0.31	0.4	V
Output High Current	I_{OH2B}	$V_{OH} = 1.7 \text{ V}$		-39	-21	mA
Output Low Current	I_{OL2B}	$V_{OL} = 0.7 \text{ V}$	22	26		mA
Rise Time ¹	t_{r2B}	$V_{OL} = 0.4 \text{ V}, V_{OH} = 2.0 \text{ V}$		1.3	1.6	ns
Fall Time ¹	$t_{\rm f2B}$	$V_{OH} = 2.0 \text{ V}, V_{OL} = 0.4 \text{ V}$		1.4	1.6	ns
Duta Carala ¹	d_{t2B}	$V_T = 1.25 \text{ V}, < 133 \text{ MHz}$	45	47.5	55	- %
Duty Cycle ¹	u _{t2B}	$V_T = 1.25 \text{ V}, >= 133 \text{ MHz}$	42	47	52	70
Skew window ¹	t _{sk2B}	$V_{T} = 1.25 \text{ V}$		70	175	ps
Jitter, Cycle-to-cycle ¹	t _{jcyc-cyc2B}	$V_T = 1.25 \text{ V}$		200	300	ps

¹Guaranteed by design, not 100% tested in production.



Electrical Characteristics - PCI

 T_A = 0 - 70C; V_{DD} = V_{DDL} = 3.3 V +/-5%; C_L = 30 pF

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output High Voltage	V_{OH1}	$I_{OH} = -18 \text{ mA}$	2.4	3		V
Output Low Voltage	V_{OL1}	$I_{OL} = 9.4 \text{ mA}$		0.2	0.4	V
Output High Current	I_{OH1}	$V_{OH} = 2.0 \text{ V}$		-62	-33	mA
Output Low Current	I_{OL1}	$V_{OL} = 0.8 \text{ V}$	38	43		mA
Rise Time ¹	t_{r1}	$V_{OL} = 0.4 \text{ V}, V_{OH} = 2.4 \text{ V}$		1.5	2	ns
Fall Time ¹	t_{f1}	$V_{OH} = 2.4 \text{ V}, V_{OL} = 0.4 \text{ V}$		1.5	2	ns
Duty Cycle ¹	d_{t1}	$V_T = 1.5 \text{ V}$	45	50	55	%
Skew window ¹	t_{sk1}	$V_T = 1.5 \text{ V}$		180	500	ps
Jitter, One Sigma ¹	t_{j1s1}	$V_T = 1.5 \text{ V}$		15	150	ps
Jitter, Absolute ¹	$\mathbf{t}_{\mathrm{jabs1}}$	$V_T = 1.5 \text{ V}$	-250	75	250	ps

Guaranteed by design, not 100% tested in production.

Electrical Characteristics - SDRAM

 $T_A = 0 - 70C$; $V_{DD} = V_{DDL} = 3.3 \text{ V +/-5\%}$; $C_L = 30 \text{ pF}$

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output High Voltage	V_{OH3}	$I_{OH} = -28 \text{ mA}$	2.4	3		V
Output Low Voltage	V_{OL3}	$I_{OL} = 19 \text{ mA}$		0.3	0.4	V
Output High Current	I_{OH3}	$V_{OH} = 2.0 \text{ V}$		-69	-46	mA
Output Low Current	I_{OL3}	$V_{OL} = 0.8 \text{ V}$	32	42		mA
Rise Time ¹	T_{r3}	$V_{OL} = 0.4 \text{ V}, V_{OH} = 2.4 \text{ V}$		1	1.3	ns
Fall Time ¹	T_{f3}	$V_{OH} = 2.4 \text{ V}, V_{OL} = 0.4 \text{ V}$		1.3	2	ns
Duty Cycle ¹	D_{t3}	$V_T = 1.5 \text{ V}$	45	50	55	%
Skew window ¹	T_{sk3}	$V_T = 1.5 \text{ V}$		185	250	ps
Propagation Time ¹ (Buffer In to output)	T_{sk3}	$V_T = 1.5 \text{ V}$		4	5	ns

 $^{^1\}mbox{Guaranteed}$ by design, not 100% tested in production.

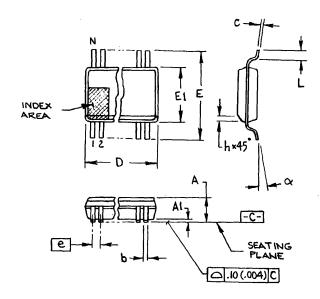


Electrical Characteristics - 24,48MHz, REF(0:1) $T_A = 0 - 70C; \ V_{DD} = V_{DDL} = 3.3 \ V + /-5\%; \ C_L = 10 - 20 \ pF \ (unless \ otherwise \ stated)$

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output High Voltage	V_{OH5}	$I_{OH} = -14 \text{ mA}$	2.4	2.6		V
Output Low Voltage	V_{OL5}	$I_{OL} = 6 \text{ mA}$		0.22	0.4	V
Output High Current	I_{OH5}	$V_{OH} = 2.0 \text{ V}$		-32	-20	mA
Output Low Current	I_{OL5}	$V_{OL} = 0.8 \text{ V}$	16	22		mA
Rise Time ¹	t_{r5}	$V_{OL} = 0.4 \text{ V}, V_{OH} = 2.4 \text{ V}$		2	4	ns
Fall Time ¹	$t_{ m f5}$	$V_{OH} = 2.4 \text{ V}, V_{OL} = 0.4 \text{ V}$		2	4	ns
Duty Cycle ¹	d _{t5}	$V_T = 1.5 \text{ V}$	45	1	55	%
Jitter, One Sigma ¹	t_{j1s5}	$V_T = 1.5 \text{ V}$		150	250	ps
Jitter, Absolute ¹	$t_{\rm jabs5}$	$V_T = 1.5 \text{ V}$	-600		600	ps

¹Guaranteed by design, not 100% tested in production.





300 mil SSOP

SYMBOL	In Millin COMMON D		in Inch	
	MIN	MAX	MIN	MAX
Α	2.40	2.80	.095	.110
A1	0.20	0.40	.008	.016
b	0.20	0.34	.008	.0135
С	0.13	0.25	.005	.010
D	SEE VARIATIONS		SEE VARIATIONS	
E	10,00	10.70	.395	.420
E1	7.40	7.60	.291	.299
е	0.065 BA	ASIC	0.025 F	BASIC
h	0.40	0.65	.015	.025
L	0.50	1.00	.020	.040
N	SEE VAR	NATIONS	SEE VARI	ATIONS
α	0°	8°	0°	8°

D mm

MIN

9.40

11.30

15.75

18.30

20.80

MAX

9.65

11.55

16.00

18.55

21.05

Ordering Information

ICS9248yF-101-T

Example:

ICS XXXX y F - PPP - T

Designation for tape and reel packaging

Pattern Number (2 or 3 digit number for parts with ROM code patterns)

Package Type
F=SSOP

Revision Designator (will not correlate with datasheet revision)

Device Type (consists of 3 or 4 digit numbers)

Prefix

ICS, AV = Standard Device

VARIATIONS

Ν

28

34

48

56

64

D (inch)

MAX

.380

455

.630

.730

MIN

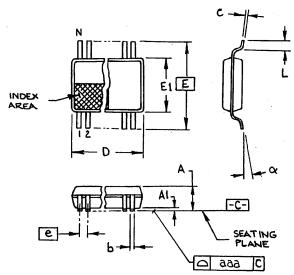
.370

.445

.620

.720





6.10 mm. Body, 0.50 mm. pitch TSSOP (240 mil) (0.020 mil)

SYMBOL	In Millin COMMON DI		In Inc	
	MIN	MAX	MIN	MAX
Α		1.20		.047
A1	0.05	0.15	.002	.006
A2	0.80	1.05	.032	.041
b	0.17	0.27	.007	.011
С	0.09	0.20	.0035	.008
D	SEE VARIATIONS		SEE VARIATIONS	
E	8.10 B	ASIC	. 0.319 BASIC	
E1	6.00	6.20	.236	.244
е	0.50 BASIC		0.020 BASIC	
L.	0.45	0.75	.018	.030
N	SEE VAR	SEE VARIATIONS		IATIONS
α	0°	8°	0°	8°
aaa		0.10		.004

Ordering Information ICS9248yG-101-T

N	D	D mm.		nch)
	MIN	MAX	MIN	MAX
28	7.70	7.90	.303	.311
_36	9.60	9.80	.378	.386
40	10.90	11.10	.429	.437
44	10.90	11.10	.429	.437
48	12.40	12.60	.488	.496
56	13.90	14.10	.547	.555
64	16.90	17.10	.665	.673

